

WHAT IS CLAIMED IS:

1. A method of producing a display panel including
a step of forming a panel having a pattern layer on a substrate
5 and a dielectric layer for covering the pattern layer, the
forming step comprising:

a first step of forming a pattern-forming material layer
having a predetermined pattern on the substrate through an
injection coating method;

10 a second step of forming a dielectric-layer forming
material layer in such a manner as to cover the pattern-forming
material layer formed at the first step; and

a third step of simultaneously calcining the
pattern-forming material layer and the dielectric-layer
15 forming material layer.

2. A method of producing a display panel according
to claim 1, wherein

the pattern-forming material layer contains silver, resin
20 and glass powder.

3. A method of producing a display panel according
to claim 1, wherein

the pattern-forming material layer includes black
25 inorganic pigments, resin and glass powder.

4. A method of producing a display panel according to claims 1, wherein the injection coating method is an ink-jet method.

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5. A method of producing a display panel according to claims 1, wherein the injection coating method is a dispenser method.

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6. A method of producing a display panel including a step of forming bus-electrode material layers for forming bus electrodes of two-layer structure having a black layer and a main conductive layer on transparent electrodes formed on a substrate; the forming step comprising:

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a first step of using a dispenser method for forming black material layers on the respective transparent electrodes and drying the black material layers; and

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a second step of using an ink-jet method for forming main conductive material layers on the respective black material layers.

7. A method of producing a display panel according to claim 6, further comprising the steps of:

forming a dielectric material layer so as to cover the transparent electrodes and the bus-electrode material layers;

and

simultaneously calcining the bus-electrode material layers and the dielectric material layer.